

4M x 16Bit CMOS Dynamic RAM with Extended Data Out

DESCRIPTION

This is a family of 4,194,304 x16 bit Extended Data Out Mode CMOS DRAMs. Extended Data Out Mode offers high speed random access of memory cells within the same row. Refresh cycle(4K Ref. or 8K Ref.), access time(-5, -6 or -7) and power consumption(Normal or Low power) are optional features of this family. All of this family have $\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$ refresh, $\overline{\text{RAS}}$ -only refresh and Hidden refresh capabilities. Further- more, self-refresh operation is available in L- version. This 4Mx16 EDO Mode DRAM family is fabricated using Samsung's advanced CMOS process to realize high band-width, low power consumption and high reliability.

FEATURES

• Part Identification

- KM416V4004A/A-L (3.3V, 8K Ref.)
- KM416V4104A/A-L (3.3V, 4K Ref.)

• Active Power Consumption

Unit : mW

Speed	8K	4K
-5	396	540
-6	360	504
-7	324	468

• Refresh cycles

Part NO.		Refresh time	
		Normal	L-ver
KM416V4004A*	8K	64ms	128ms
KM416V4104A	4K		

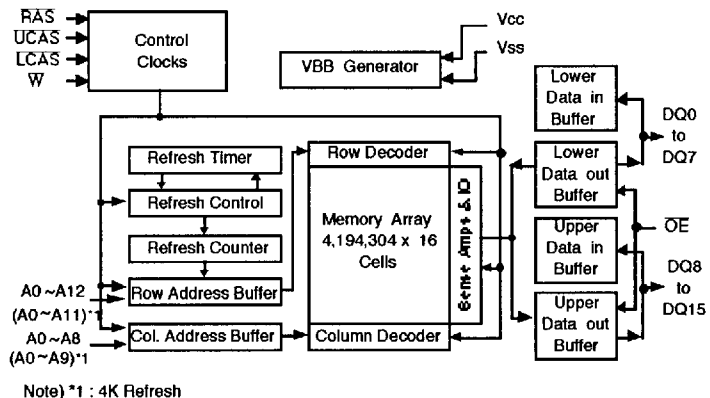
* Access mode & $\overline{\text{RAS}}$ only refresh mode : 8K cycle/64ms
 $\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$ & Hidden refresh mode : 4K cycle/64ms

• Performance range:

Speed	tRAC	tCAC	tRC	tHPC
-5	50ns	13ns	84ns	20ns
-6	60ns	15ns	104ns	25ns
-7	70ns	17ns	124ns	30ns

- Extended Data Out Mode operation
- 2 $\overline{\text{CAS}}$ Byte/Word Read/Write operation
- $\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$ refresh capability
- $\overline{\text{RAS}}$ -only and Hidden refresh capability
- Self-refresh capability(L-ver only)
- LVTTTL(3.3V) compatible inputs and outputs
- Early Write or output enable controlled write
- JEDEC Standard pinout
- Available in Plastic TSOP(II) package
- +3.3V±0.3V power supply

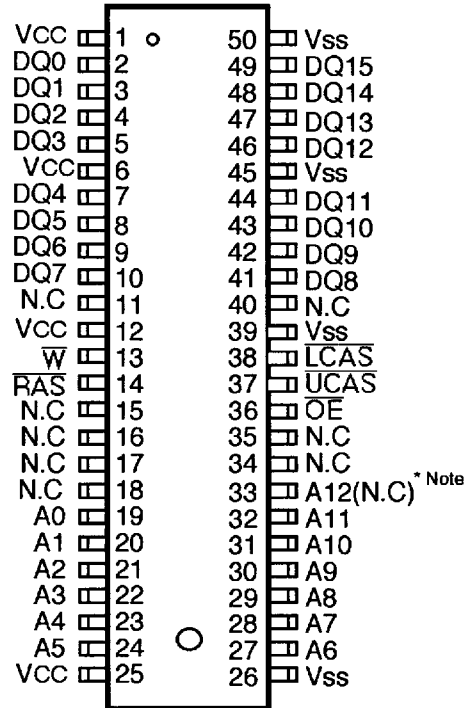
FUNCTIONAL BLOCK DIAGRAM



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PIN CONFIGURATION (Top Views)

• KM416V40(1)04AS



* Note : A12 --> 8K Product(KM416V4004A)
N.C --> 4K Product(KM416V4104A)

Pin Name	Pin Function
A0 - A12	Address Inputs(8K Product)
A0 - A11	Address Inputs(4K Product)
DQ0 -15	Data In/Out
Vss	Ground
\overline{RAS}	Row Address Strobe
\overline{UCAS}	Upper Column Address Strobe
LCAS	Lower Column Address Strobe
\overline{W}	Read/Write Input
\overline{OE}	Data Outputs Enable
VCC	Power(+3.3V)
N.C	No Connection

ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Rating	Units
		3.3V	
Voltage on any pin relative to V _{SS}	V _{IN} , V _{OUT}	-0.5 to +4.6	V
Voltage on V _{CC} supply relative to V _{SS}	V _{CC}	-0.5 to +4.6	V
Storage Temperature	T _{stg}	-55 to +150	°C
Power Dissipation	P _D	1	W
Short Circuit Output Current	I _{OS}	50	mA

* Permanent device damage may occur if "ABSOLUTE MAXIMUM RATINGS" are exceeded. Functional operation should be restricted to the conditions as detailed in the operational sections of this data sheet. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

RECOMMENDED OPERATING CONDITIONS (Voltages referenced to V_{SS}, T_A= 0 to 70 °C)

Parameter	Symbol	Min	Typ	Max	Unit
Supply Voltage	V _{CC}	3.0	3.3	3.6	V
Ground	V _{SS}	0	0	0	V
Input High Voltage	V _{IH}	2.0	-	V _{CC} +0.3 *1	V
Input Low Voltage	V _{IL}	-0.3 *2	-	0.8	V

*1 : V_{CC} + 1.3V/15ns, Pulse width is measured at V_{CC}.

*2 : - 1.3V/15ns, Pulse width is measured at V_{SS}.

DC AND OPERATING CHARACTERISTICS (Recommended operating conditions unless otherwise noted.)

Parameter	Symbol	Min	Max	Units
Input Leakage Current (Any input 0 ≤ V _{IN} ≤ V _{CC} +0.3V, all other pins not under test=0 volt.)	I _{I(L)}	- 5	5	μA
Output Leakage Current (Data out is disabled, 0V ≤ V _{OUT} ≤ V _{CC})	I _{O(L)}	- 5	5	μA
Output High Voltage Level(I _{OH} =-2mA)	V _{OH}	2.4	-	V
Output Low Voltage Level(I _{OL} =2mA)	V _{OL}	-	0.4	V

DC AND OPERATING CHARACTERISTICS (Recommended operating conditions unless otherwise noted.)

Symbol	Power	Speed	Max		Units
			KM416V4004A	KM416V4104A	
I _{cc1}	Don't care	-5	110	150	mA
		-6	100	140	mA
		-7	90	130	mA
I _{cc2}	Normal L	Don't care	2	2	mA
			2	2	mA
I _{cc3}	Don't care	-5	110	150	mA
		-6	100	140	mA
		-6	90	130	mA
I _{cc4}	Don't care	-5	110	120	mA
		-6	100	110	mA
		-7	90	100	mA
I _{cc5}	Normal L	Don't care	500	500	μA
			300	300	μA
I _{cc6}	Don't care	-5	150	150	mA
		-6	140	140	mA
		-7	130	130	mA
I _{cc7}	L	Don't care	550	550	μA
I _{cc8}	L	Don't care	450	450	μA

I_{cc1}* : Operating Current (\overline{RAS} , \overline{UCAS} , \overline{LCAS} , Address cycling @t_{RC}=min.)

I_{cc2} : Standby Current ($\overline{RAS}=\overline{UCAS}=\overline{LCAS}=\overline{W}=V_{IH}$)

I_{cc3}* : \overline{RAS} -Only Refresh Current ($\overline{UCAS}=\overline{LCAS}=V_{IH}$, \overline{RAS} , Address cycling @t_{RC}=min.)

I_{cc4}* : Fast Page Mode Current ($\overline{RAS}=V_{IL}$, \overline{UCAS} or \overline{LCAS} , Address cycling @t_{HPC}=min.)

I_{cc5} : Standby Current ($\overline{RAS}=\overline{UCAS}=\overline{LCAS}=\overline{W}=V_{CC}-0.2V$)

I_{cc6}* : \overline{CAS} -before- \overline{RAS} Refresh Current (\overline{RAS} , \overline{UCAS} or \overline{LCAS} cycling @t_{RC}=min.)

I_{cc7} : Battery back-up current, Average power supply current, Battery back-up mode

Input high voltage(V_{IH})=V_{CC}-0.2V, Input low voltage(V_{IL})=0.2V, \overline{UCAS} , \overline{LCAS} = 0.2V,

Din = Don't care, t_{RC}= 31.25μs, t_{RAS}=t_{RASmin}~300 ns

I_{cc8} : Self Refresh Current

$\overline{RAS}=\overline{UCAS}=\overline{LCAS}=V_{IL}$, $\overline{W}=\overline{OE}=A0 \sim A12(11)=V_{CC}-0.2V$ or 0.2V,

DQ0 ~ DQ15= V_{CC}-0.2V, 0.2V or Open

* NOTE : I_{cc1}, I_{cc3}, I_{cc4} and I_{cc6} are dependent on output loading and cycle rates. Specified values are obtained with the output open. I_{cc} is specified as an average current. In I_{cc1}, I_{cc3}, and I_{cc6}, address can be changed maximum once while $\overline{RAS}=V_{IL}$. In I_{cc4}, address can be changed maximum once within one EDO mode cycle time t_{HPC}.

CAPACITANCE($T_A=25^\circ\text{C}$, $V_{CC}=3.3\text{V}$, $f=1\text{MHz}$)

Parameter	Symbol	Min	Max	Unit
Input capacitance [A0 - A12]	C_{IN1}	-	5	pF
Input capacitance [RAS, CAS, W, OE]	C_{IN2}	-	7	pF
Output Capacitance [DQ0 - DQ15]	C_{DQ}	-	7	pF

AC CHARACTERISTICS ($0^\circ\text{C} \leq T_A \leq 70^\circ\text{C}$, See note 2)

Test condition : $V_{CC}=3.3\text{V} \pm 0.3\text{V}$, $V_{IH}/V_{IL}=2.2/0.7\text{V}$, $V_{OH}/V_{OL}=2.0/0.8\text{V}$

Parameter	Symbol	- 5		- 6		- 7		Units	Notes
		Min	Max	Min	Max	Min	Max		
Random read or write cycle time	tRC	84		104		124		ns	
Read-modify-write cycle time	tRWC	116		140		170		ns	
Access time from RAS	tRAC		50		60		70	ns	3,4,10
Access time from CAS	tCAC		13		15		17	ns	3,4,5
Access time from column address	tAA		25		30		35	ns	3,10
CAS to output in Low-Z	tCLZ	3		3		3		ns	3
Output buffer turn-off delay from CAS	tCEZ	3	13	3	15	3	20	ns	6
OE to output in Low-Z	tOLZ	3		3		3		ns	3
Transition time (rise and fall)	tT	2	50	2	50	2	50	ns	2
RAS precharge time	tRP	30		40		50		ns	
RAS pulse width	tRAS	50	10K	60	10K	70	10K	ns	
RAS hold time	tRSH	13		15		20		ns	
CAS hold time	tCSH	38		45		50		ns	
CAS pulse width	tCAS	8	10K	10	10K	15	10K	ns	15
RAS to CAS delay time	tRCD	20	37	20	45	20	50	ns	4
RAS to column address delay time	tRAD	15	25	15	30	15	35	ns	10
CAS to RAS precharge time	tCRP	5		5		5		ns	
Row address set-up time	tASR	0		0		0		ns	
Row address hold time	tRAH	10		10		10		ns	
Column address set-up time	tASC	0		0		0		ns	13
Column address hold time	tCAH	8		10		15		ns	13
Column address to RAS lead time	tRAL	25		30		35		ns	
Read command set-up time	tRCS	0		0		0		ns	
Read command hold time referenced to CAS	tRCH	0		0		0		ns	8
Read command hold time referenced to RAS	tRRH	0		0		0		ns	8
Write command hold time	tWCH	10		10		15		ns	
Write command pulse width	tWP	10		10		15		ns	
Write command to RAS lead time	tRWL	13		15		20		ns	
Write command to CAS lead time	tCWL	8		10		15			16

AC CHARACTERISTICS (Continued)									
Parameter	Symbol	- 5		- 6		- 7		Units	Notes
		Min	Max	Min	Max	Min	Max		
Data set-up time	tDS	0		0		0		ns	9,19
Data hold time	tDH	8		10		15		ns	9,19
Refresh period(4K, Normal)	tREF		64		64		64	ms	
Refresh period(8K, Normal)	tREF		64		64		64	ms	
Refresh period(L-ver)	tREF		128		128		128	ms	
Write command set-up time	tWCS	0		0		0		ns	7
CAS to \bar{W} delay time	tCWD	30		34		44		ns	7,15
RAS to \bar{W} delay time	tRWD	67		79		94		ns	7
Column address to \bar{W} delay time	tAWD	42		49		59		ns	7
CAS set-up time (CAS-before-RAS refresh)	tCSR	10		10		10		ns	17
CAS hold time (CAS-before-RAS refresh)	tCHR	10		10		15		ns	18
RAS to CAS precharge time	tRPC	5		5		5		ns	
Access time from CAS precharge	tCPA		28		35		40	ns	3
Hyper Page cycle time	tHPC	20		25		30		ns	20
Hyper Page read-modify-write cycle time	tHPRWC	47		56		71		ns	20
CAS precharge time (Hyper page cycle)	tCP	8		10		10		ns	14
Access time from CAS (Hyper page cycle)	tCACP		15		17		20	ns	
Access time from col. address(Hyper page)	tAAP		25		30		35	ns	
RAS pulse width (Hyper page cycle)	tRASP	50	200K	60	200K	70	200K	ns	
RAS hold time from CAS precharge	tRHCP	30		35		40		ns	
OE access time	tOEA		13		15		17	ns	
OE to data delay	tOED	13		15		20		ns	
CAS precharge to \bar{W} delay time	tCPWD	45		54		64		ns	
Out put buffer turn off delay time from OE	tOEZ	3	13	3	15	3	20	ns	6
OE command hold time	tOEH	13		15		20		ns	
Write command set-up time(Test mode in)	tWTS	10		10		10		ns	11
Write command hold time(Test mode in)	tWTH	10		10		10		ns	11
\bar{W} to RAS precharge time(C-B-R refresh)	tWRP	10		10		10		ns	
W to RAS hold time(C-B-R refresh)	tWRH	10		10		10		ns	
Output data hold time	tDOH	5		5		5		ns	
Output buffer turn off delay from RAS	tREZ	3	13	3	15	3	20	ns	6
Output buffer turn off delay from \bar{W}	tWEZ	3	13	3	15	3	20	ns	6
W to data delay	tWED	15		15		20		ns	
OE to CAS hold time	tOCH	5		5		5		ns	
CAS hold time to OE	tCHO	5		5		5		ns	
OE precharge time	tOEP	5		5		5		ns	
W pulth width(Hyper Page Cycle)	tWPE	5		5		5		ns	
RAS pulse width(C-B-R self refresh)	tHASS	100		100		100		us	21
RAS precharge time (C-B-R self refresh)	tRPS	90		110		130		ns	21
CAS hold time (C-B-R self refresh)	tCHS	-50		-50		-50		ns	21

TEST MODE CYCLE

(Note. 11)

Parameter	Symbol	-5		-6		-7		Units	Notes
		Min	Max	Min	Max	Min	Max		
Random read or write cycle time	tRC	89		109		129		ns	
Read-modify-write cycle time	tRWC	121		145		175		ns	
Access time from RAS	tRAC		55		65		75	ns	3,4,10
Access time from CAS	tCAC		18		20		25	ns	3,4,5
Access time from column address	tAA		30		35		40	ns	3,10
RAS pulse width	tRAS	55	10K	65	10K	75	10K	ns	
CAS pulse width	tCAS	13	10K	15	10K	20	10K	ns	
RAS hold time	tRSH	18		20		25		ns	
CAS hold time	tCSH	43		50		55		ns	
Column address to RAS lead time	tRAL	30		35		40		ns	
CAS to \bar{W} delay time	tCWD	35		39		49		ns	7
RAS to \bar{W} delay time	tRWD	72		84		99		ns	7
Column address to \bar{W} delay time	tAWD	47		54		64		ns	7
Hyper Page cycle time	tHPC	25		30		35		ns	
Hyper page read-modify-write cycle time	tHPRWC	53		61		76		ns	
RAS pulse width (Hyper page cycle)	tRASP	55	200K	65	200K	75	200K	ns	
Access time form CAS precharge	tCPA		33		40		45	ns	3
OE access time	tOEA		18		20		25	ns	
OE to data delay	tOED	18		20		25		ns	
OE command hold time	tOEH	18		20		25		ns	

NOTES

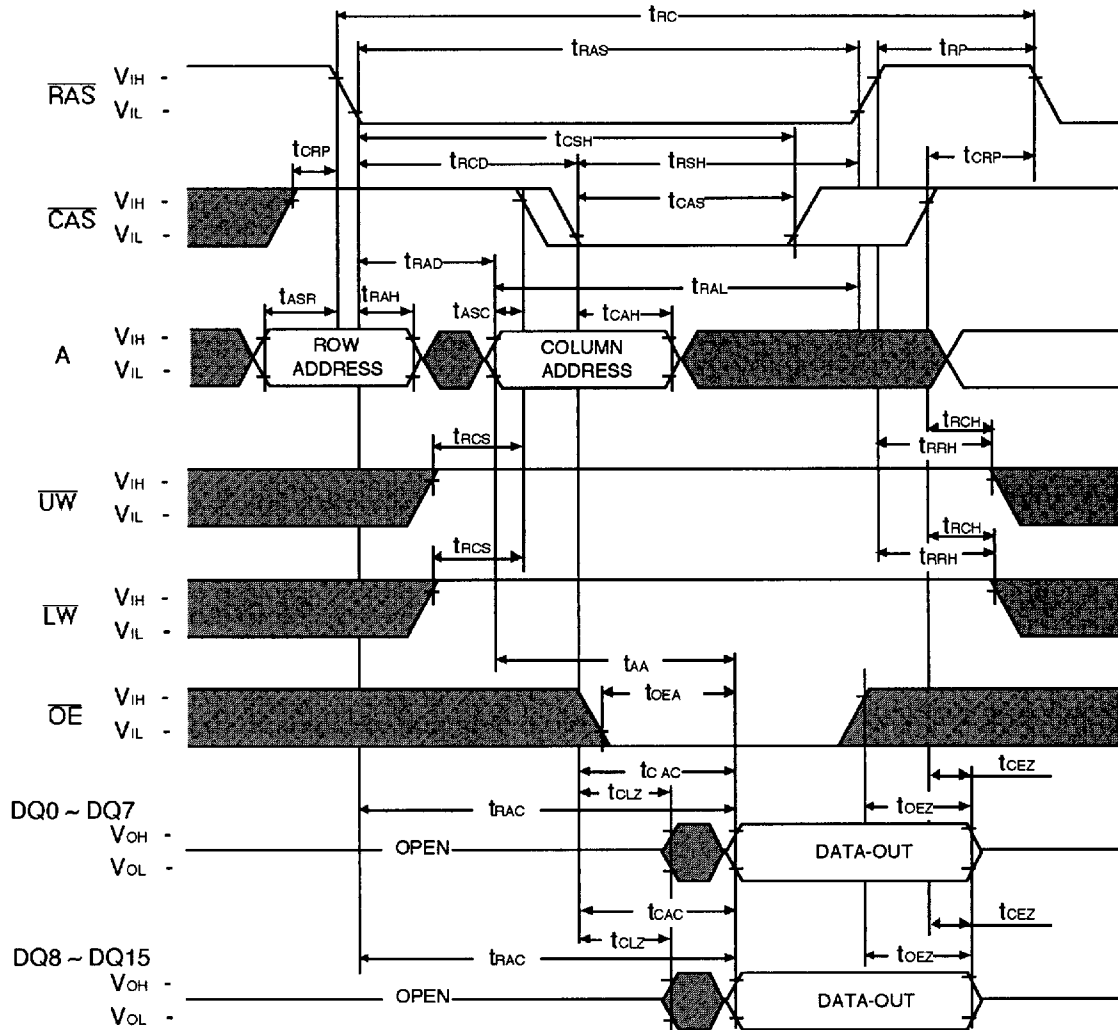
1. An initial pause of 200 μ s is required after power-up followed by any 8 $\overline{\text{RAS}}$ -only or $\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$ refresh cycles before proper device operation is achieved.
2. Input voltage levels are V_{ih}/V_{il} . $V_{ih}(\text{min})$ and $V_{il}(\text{max})$ are reference levels for measuring timing of input signals. Transition times are measured between $V_{ih}(\text{min})$ and $V_{il}(\text{max})$ and are assumed to be 2ns for all inputs.
3. Measured with a load equivalent to 1 TTL load and 100pF.
4. Operation within the $t_{\text{RCD}}(\text{max})$ limit insures that $t_{\text{RAC}}(\text{max})$ can be met. $t_{\text{RCD}}(\text{max})$ is specified as a reference point only. If t_{RCD} is greater than the specified $t_{\text{RCD}}(\text{max})$ limit, then access time is controlled exclusively by t_{CAC} .
5. Assumes that $t_{\text{RCD}} \geq t_{\text{RCD}}(\text{max})$.
6. This parameter defines the time at which the output achieves the open circuit condition and is not referenced to V_{oh} or V_{ol} .
7. t_{WCS} , t_{RWD} , t_{CWD} and t_{AWD} are non restrictive operating parameters. They are included in the data sheet as electrical characteristics only. If $t_{\text{WCS}} \geq t_{\text{WCS}}(\text{min})$, the cycles is an early write cycle and the data output will remain high impedance for the duration of the cycle. If $t_{\text{CWD}} \geq t_{\text{CWD}}(\text{min})$, $t_{\text{RWD}} \geq t_{\text{RWD}}(\text{min})$ and $t_{\text{AWD}} \geq t_{\text{AWD}}(\text{min})$, then the cycle is a read-modify-write cycle and the data output will contain the data read from the selected address. If neither of the above conditions is satisfied, the condition of the data out is indeterminate.
8. Either t_{RCH} or t_{RRH} must be satisfied for a read cycle.
9. This parameter is referenced to the $\overline{\text{CAS}}$ leading edge in early write cycles and to the $\overline{\text{W}}$ leading edge in read-modify-write cycles.
10. Operation within the $t_{\text{RAD}}(\text{max})$ limit insures that $t_{\text{RAC}}(\text{max})$ can be met. $t_{\text{RAD}}(\text{max})$ is specified as a reference point only. If t_{RAD} is greater than the specified $t_{\text{RAD}}(\text{max})$ limit, then access time is controlled by t_{AA} .
11. These specifications are applied in the test mode.

KM416V40(1)04A/A-L Truth Table

RAS	LCAS	UCAS	W	OE	DQ0 -DQ7	DQ8 - DQ15	STATE
H	X	X	X	X	Hi-Z	Hi-Z	Standby
L	H	H	X	X	Hi-Z	Hi-Z	Refresh
L	L	H	H	L	DQ-OUT	Hi-Z	Byte Read
L	H	L	H	L	Hi-Z	DQ-OUT	Byte Read
L	L	L	H	L	DQ-OUT	DQ-OUT	Word Read
L	L	H	L	H	DQ-IN	-	Byte Write
L	H	L	L	H	-	DQ-IN	Byte Write
L	L	L	L	H	DQ-IN	DQ-IN	Word Write
L	L	L	H	H	Hi-Z	Hi-Z	-

TIMING DIAGRAM
READ CYCLE

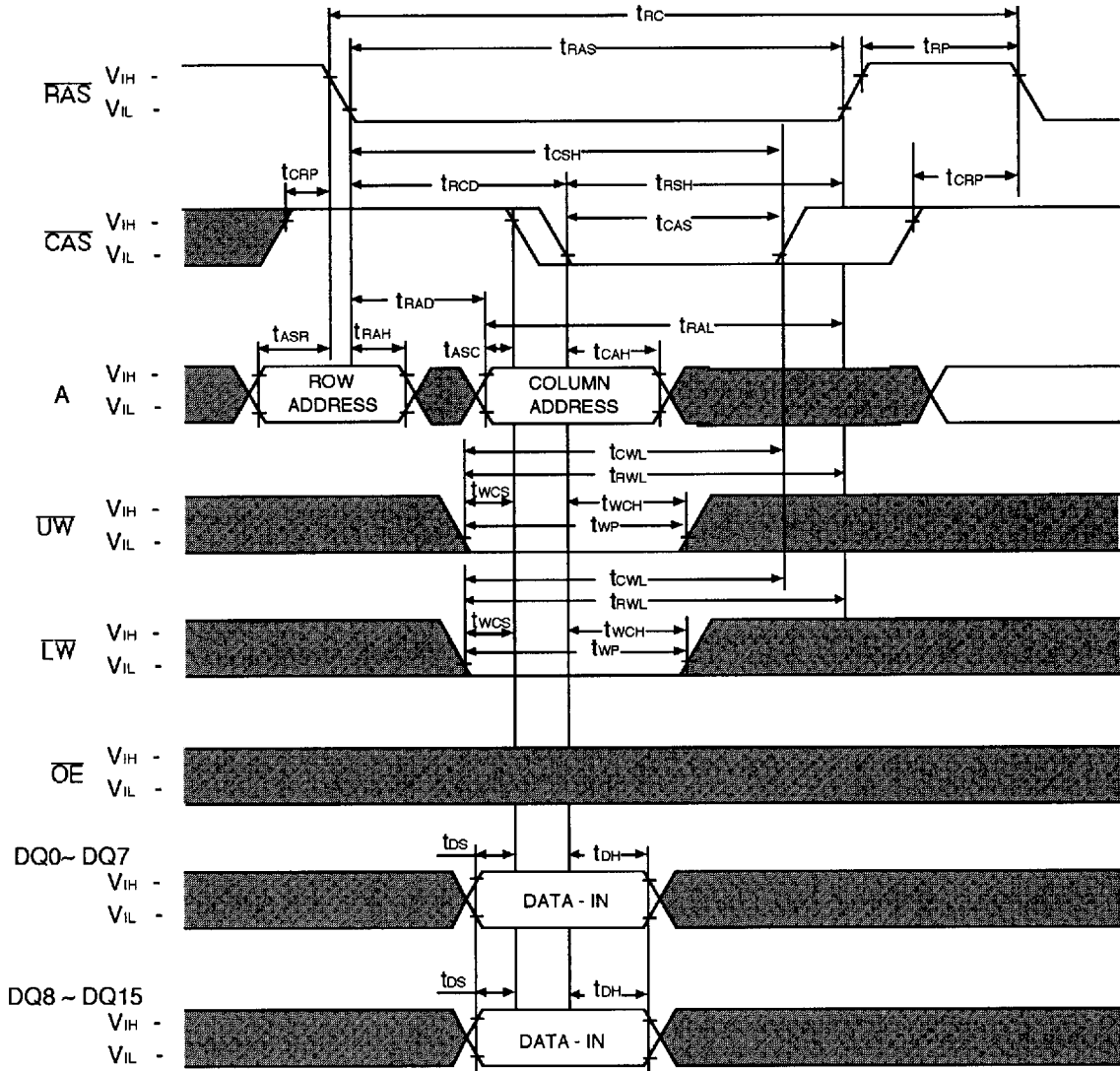
NOTE : D_{IN} = OPEN



■ Don't Care

WRITE CYCLE (EARLY WRITE)

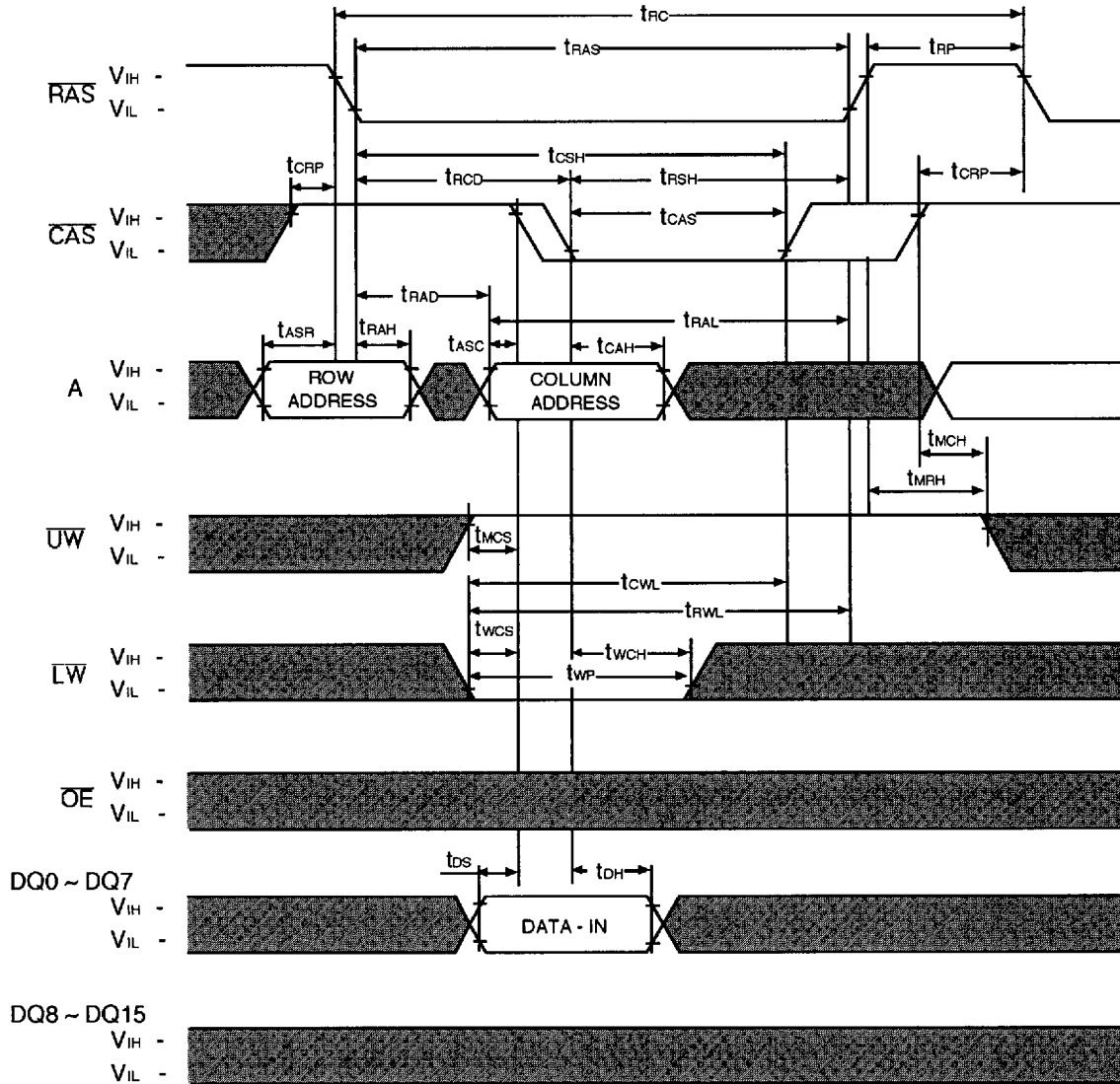
NOTE : D_{OUT} = OPEN



 Don't Care

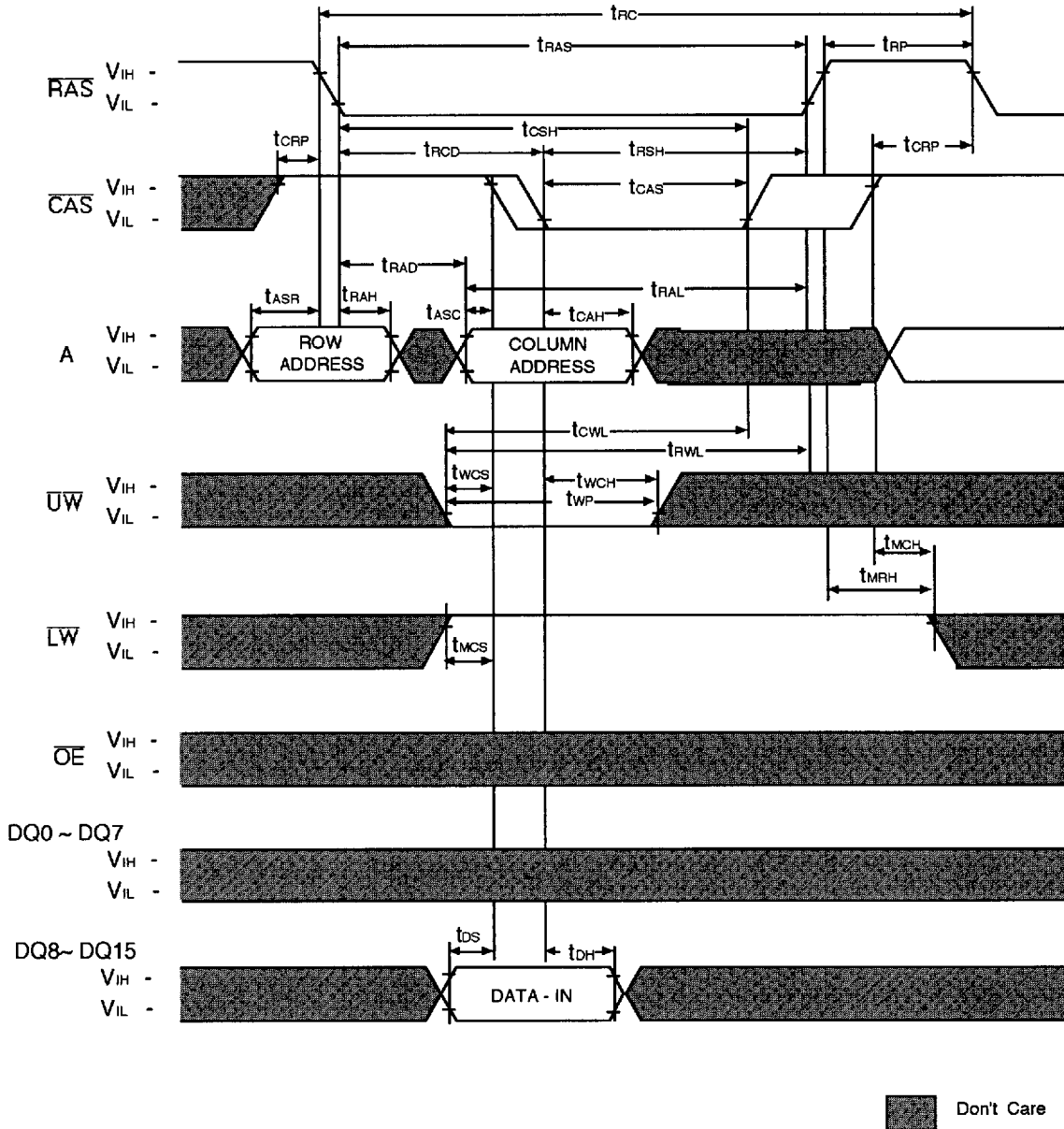
LOWER BYTE WRITE CYCLE (EARLY WRITE)

NOTE : D_{OUT} = OPEN



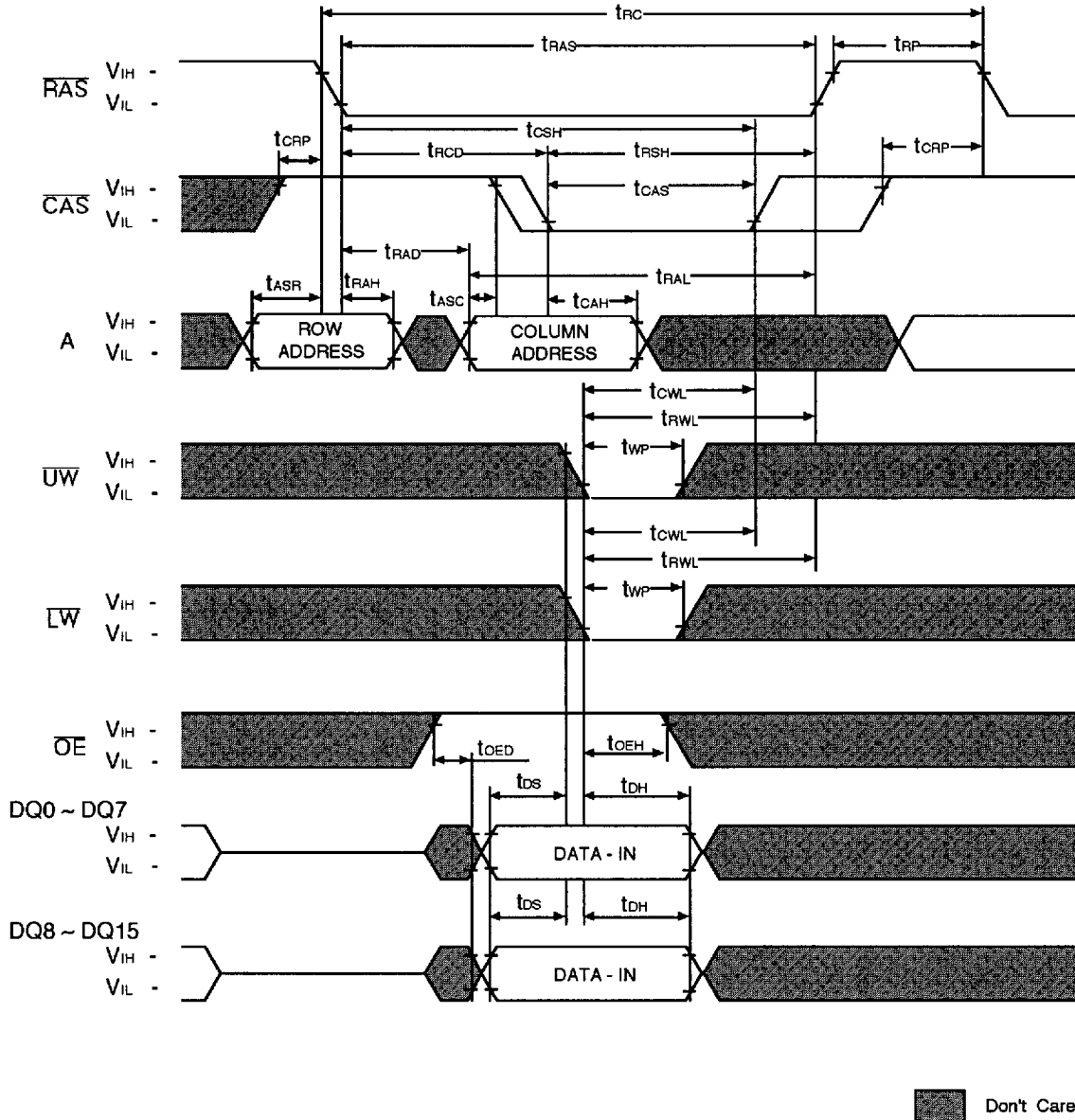
UPPER BYTE WRITE CYCLE (EARLY WRITE)

NOTE : DOUT = OPEN



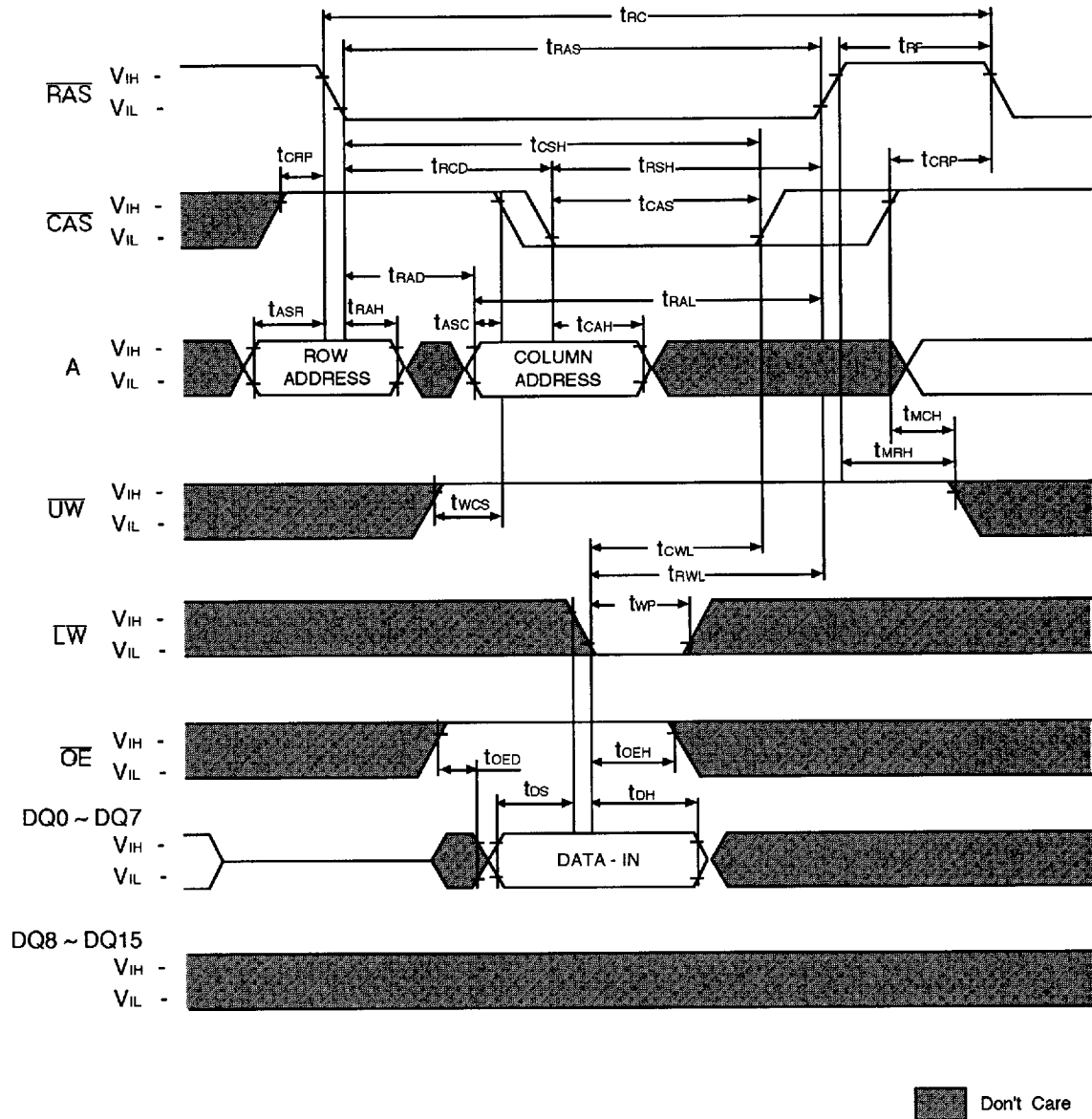
WRITE CYCLE (\overline{OE} CONTROLLED WRITE)

NOTE : D_{out} = OPEN



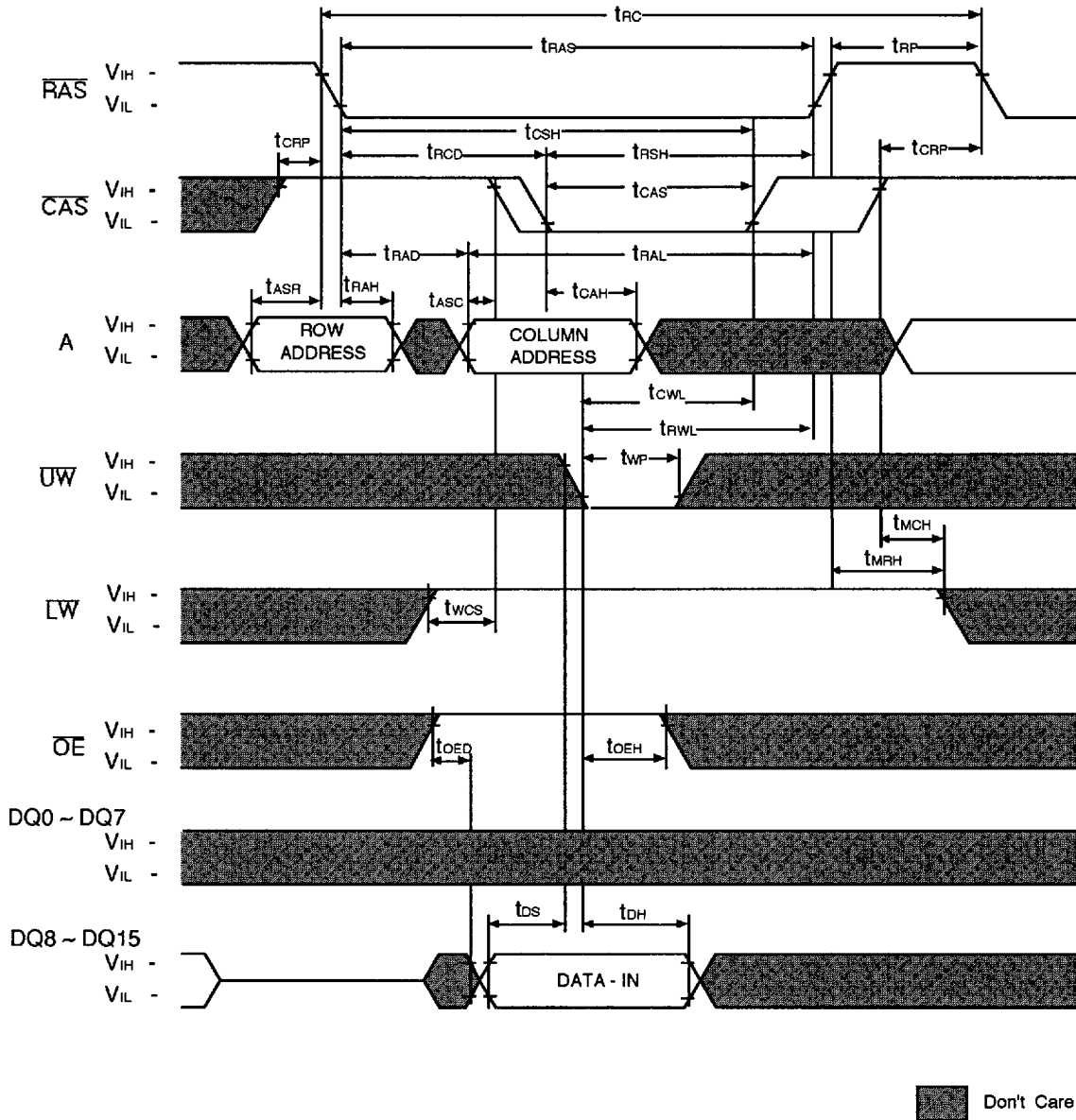
LOWER BYTE WRITE CYCLE (OE CONTROLLED WRITE)

NOTE : Dout = OPEN

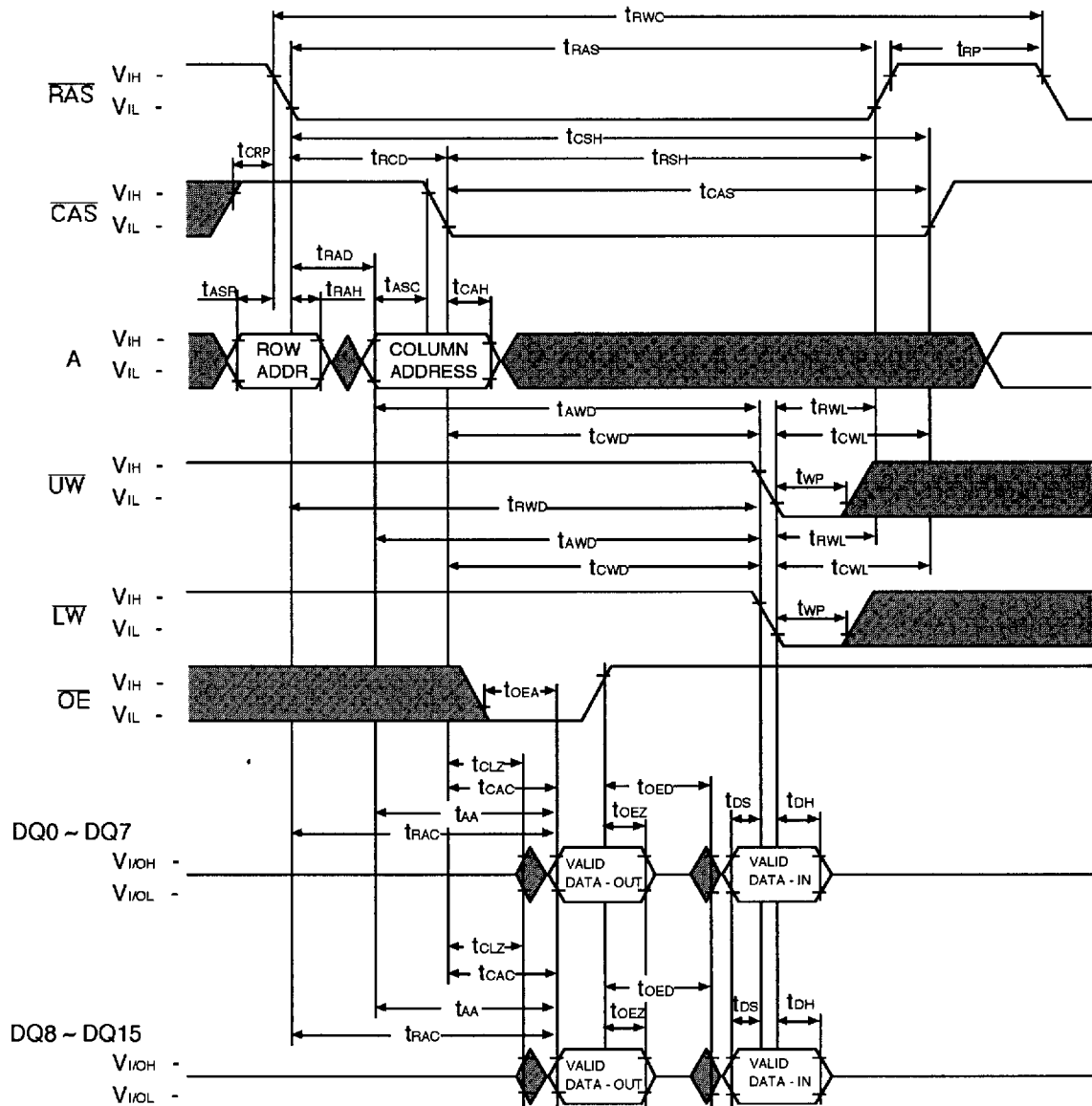


UPPER BYTE WRITE CYCLE (OE CONTROLLED WRITE)

NOTE : D_{OUT} = OPEN

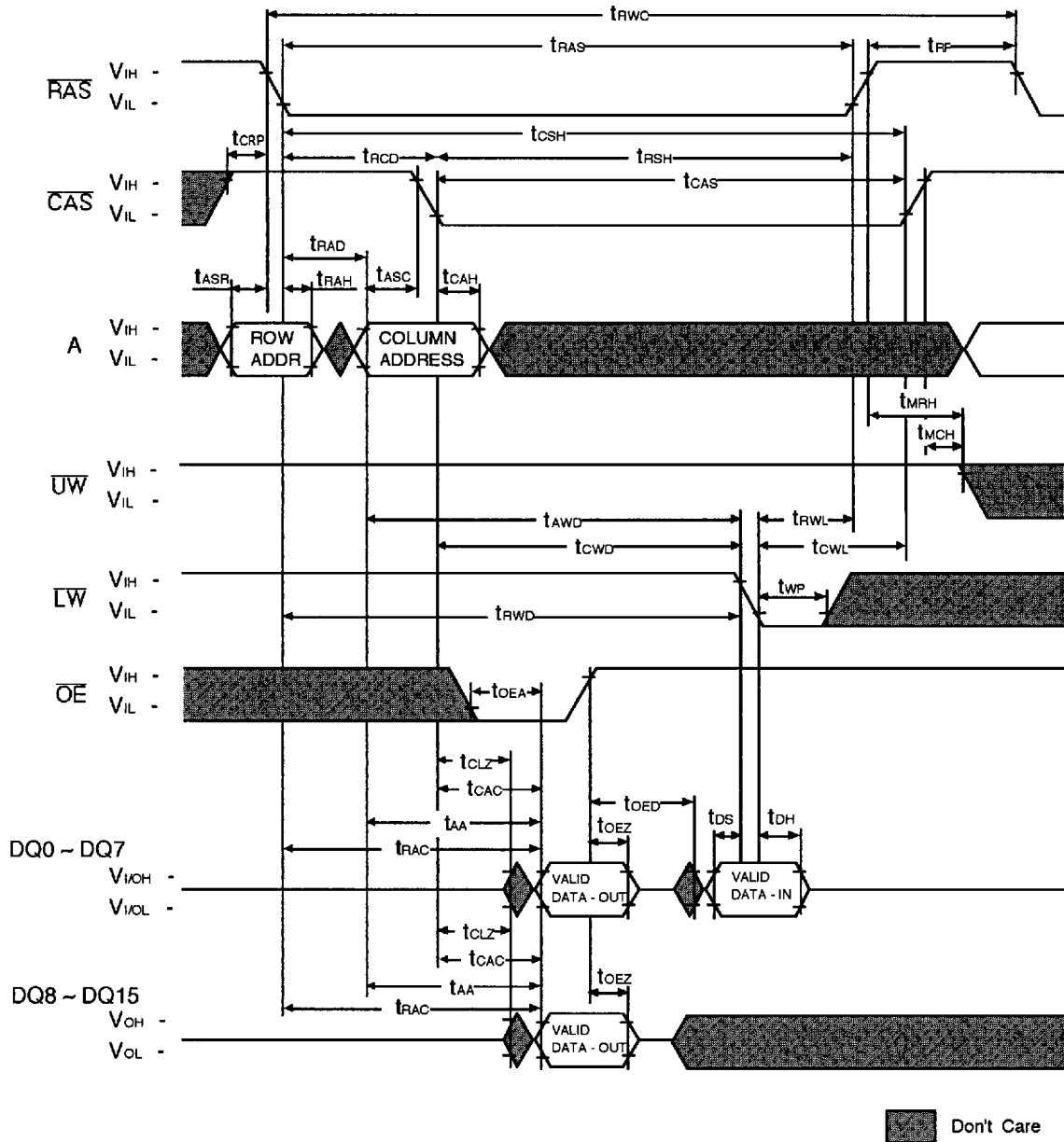


WORD READ - MODIFY - WRITE CYCLE

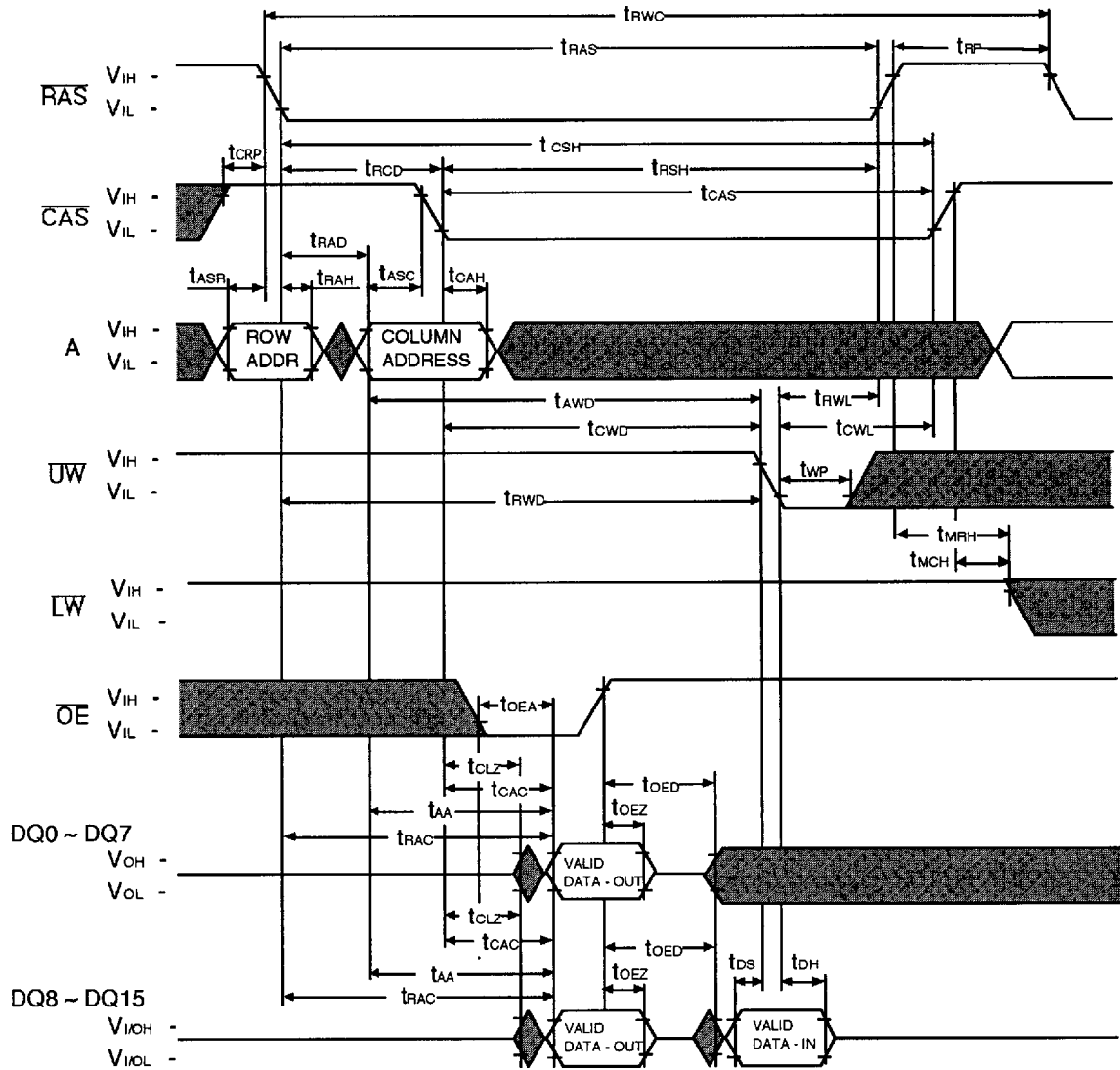


■ Don't Care

LOWER-BYTE READ - MODIFY - WRITE CYCLE

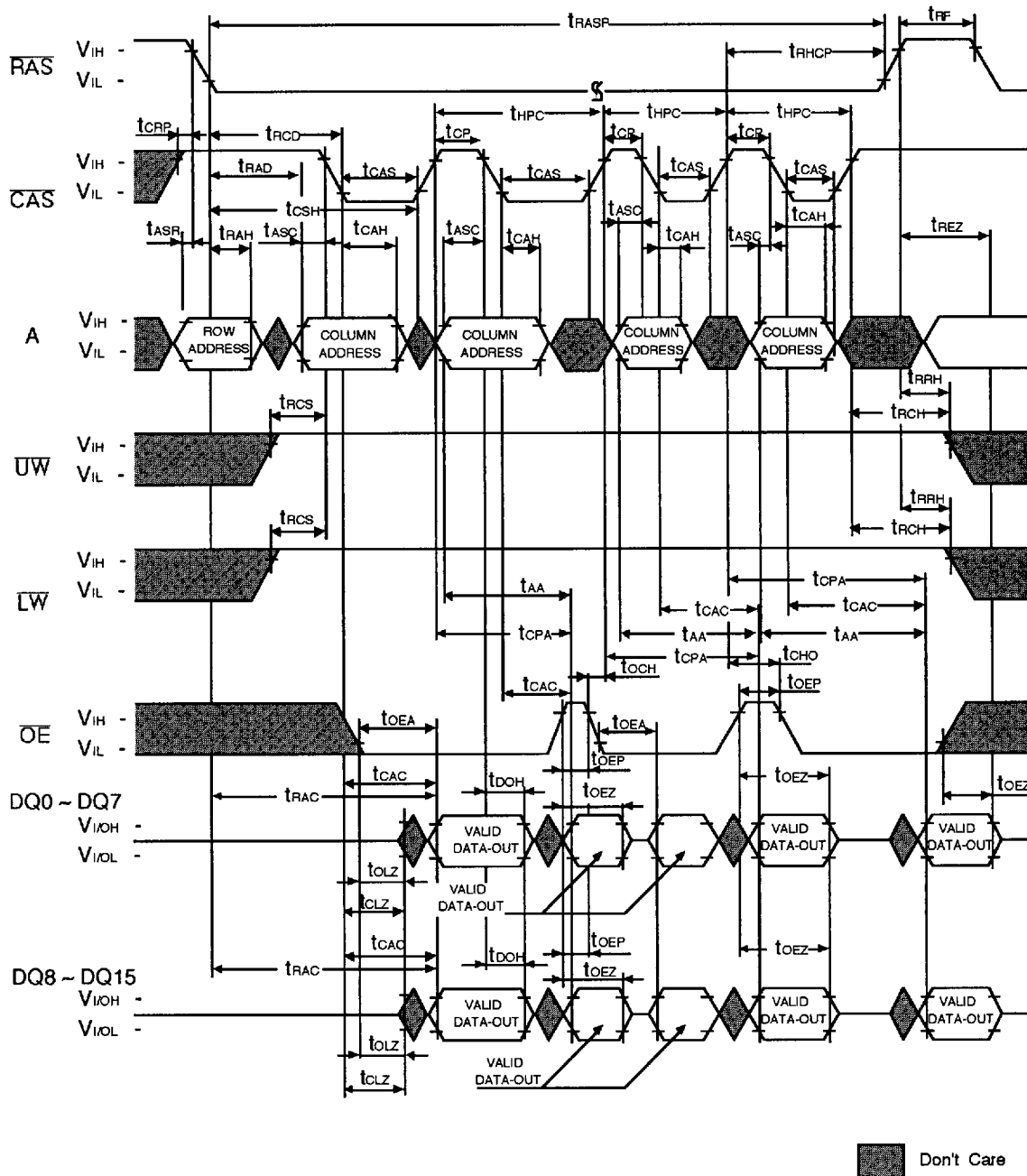


UPPER-BYTE READ - MODIFY - WRITE CYCLE



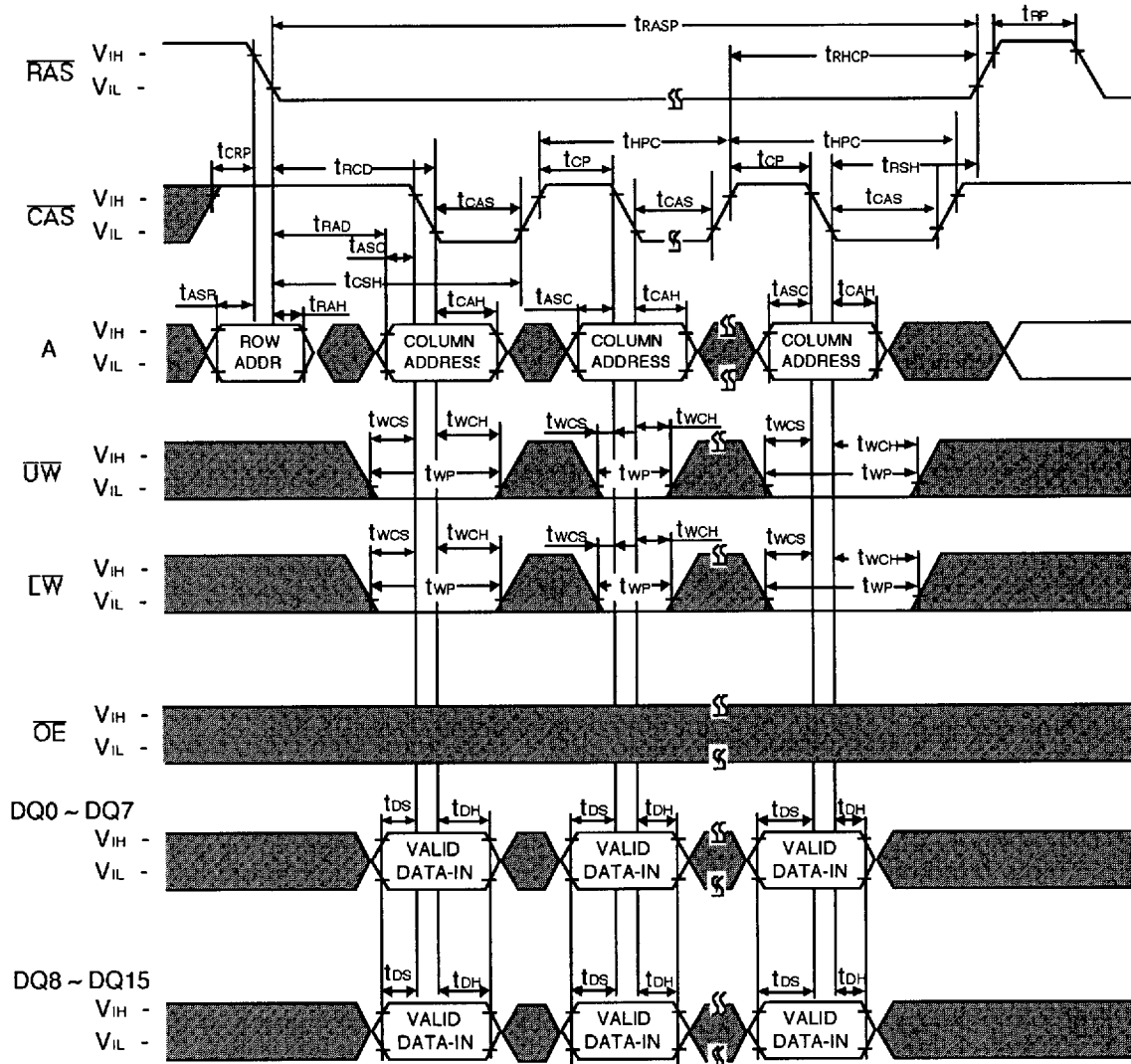
■ Don't Care


HYPER PAGE MODE WORD READ CYCLE



HYPER PAGE MODE WORD WRITE CYCLE (EARLY WRITE)

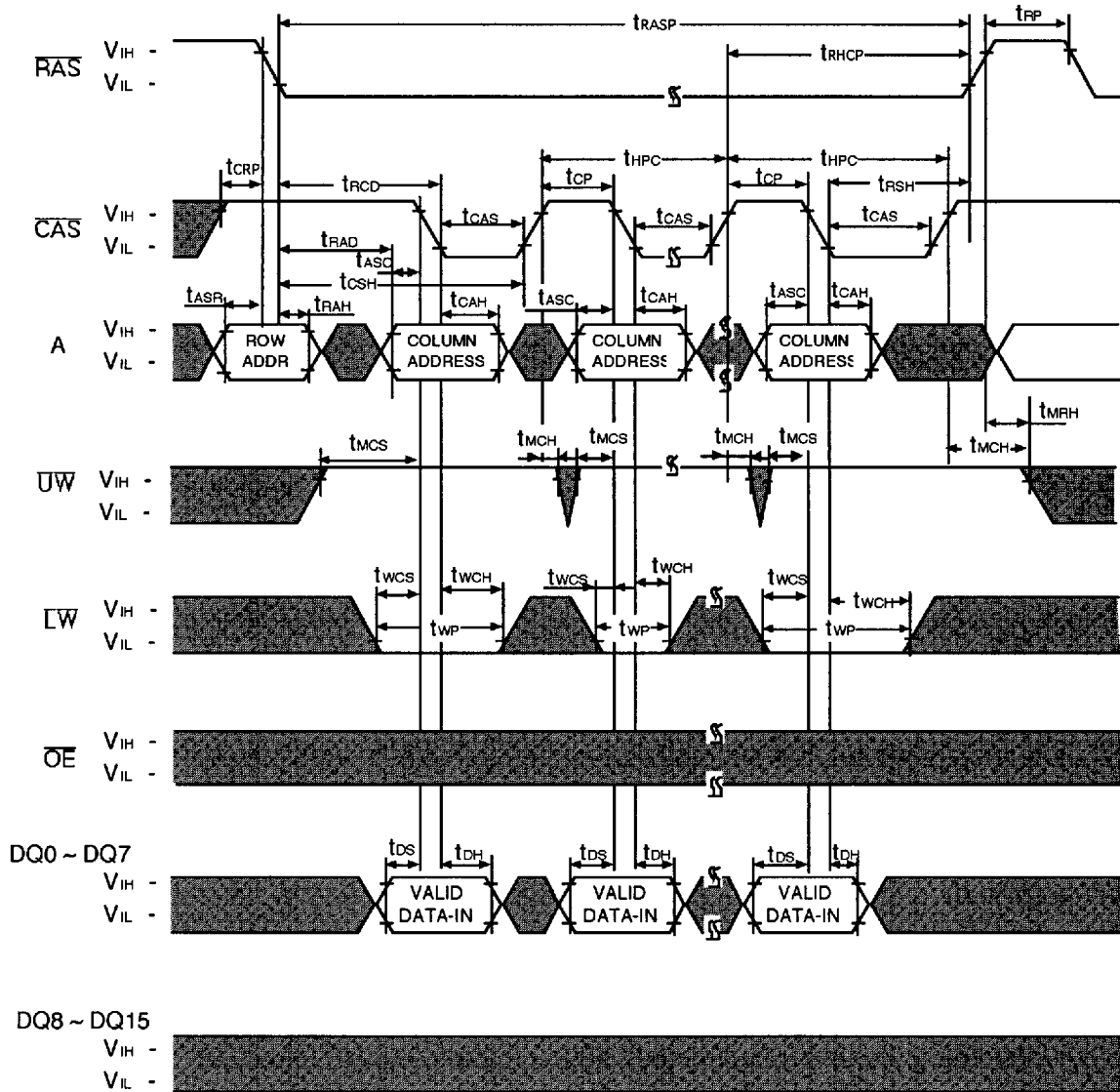
NOTE : Dout = Open



 Don't Care

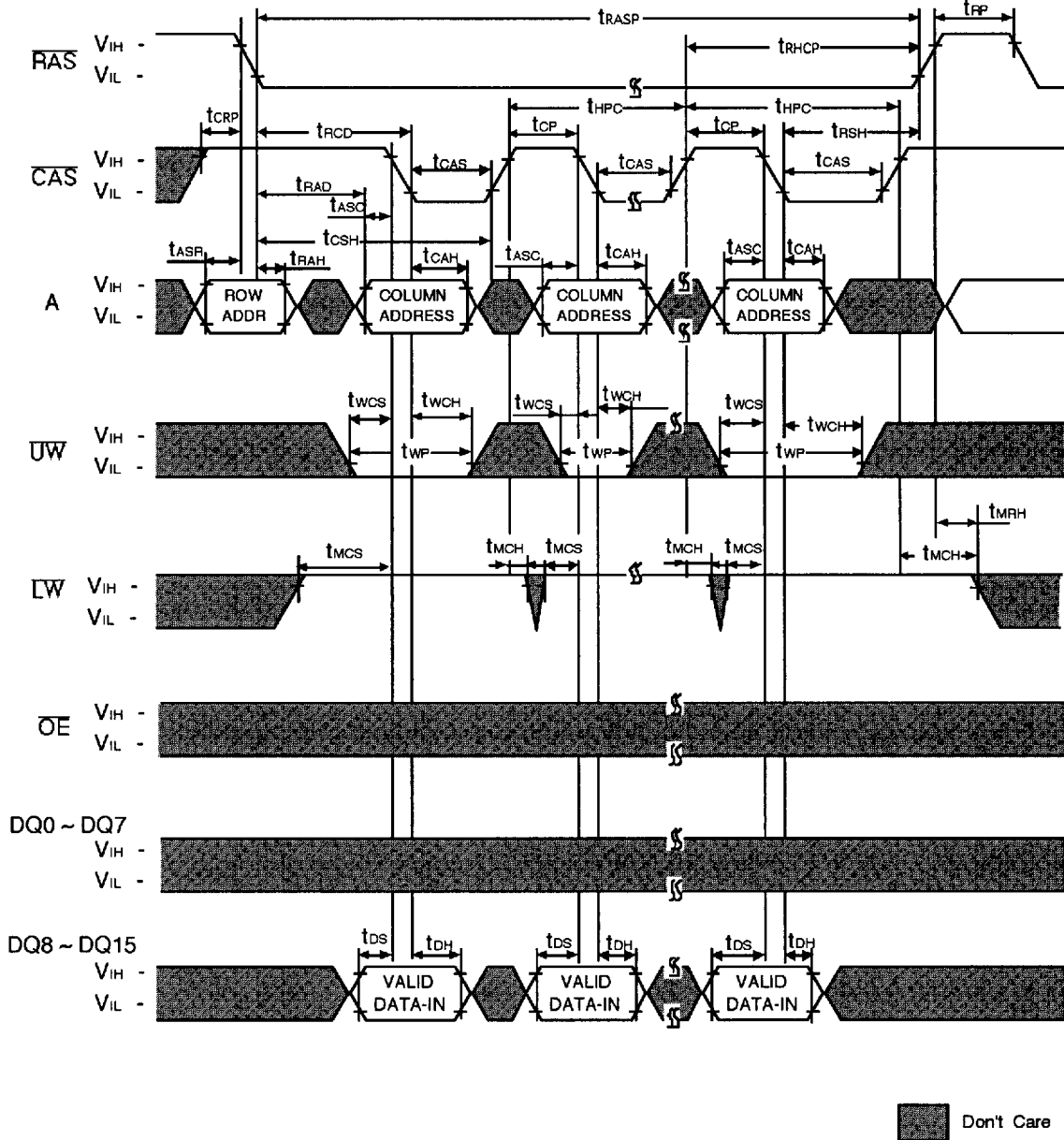
HYPER PAGE MODE LOWER BYTE WRITE CYCLE (EARLY WRITE)

NOTE : DOUT = Open

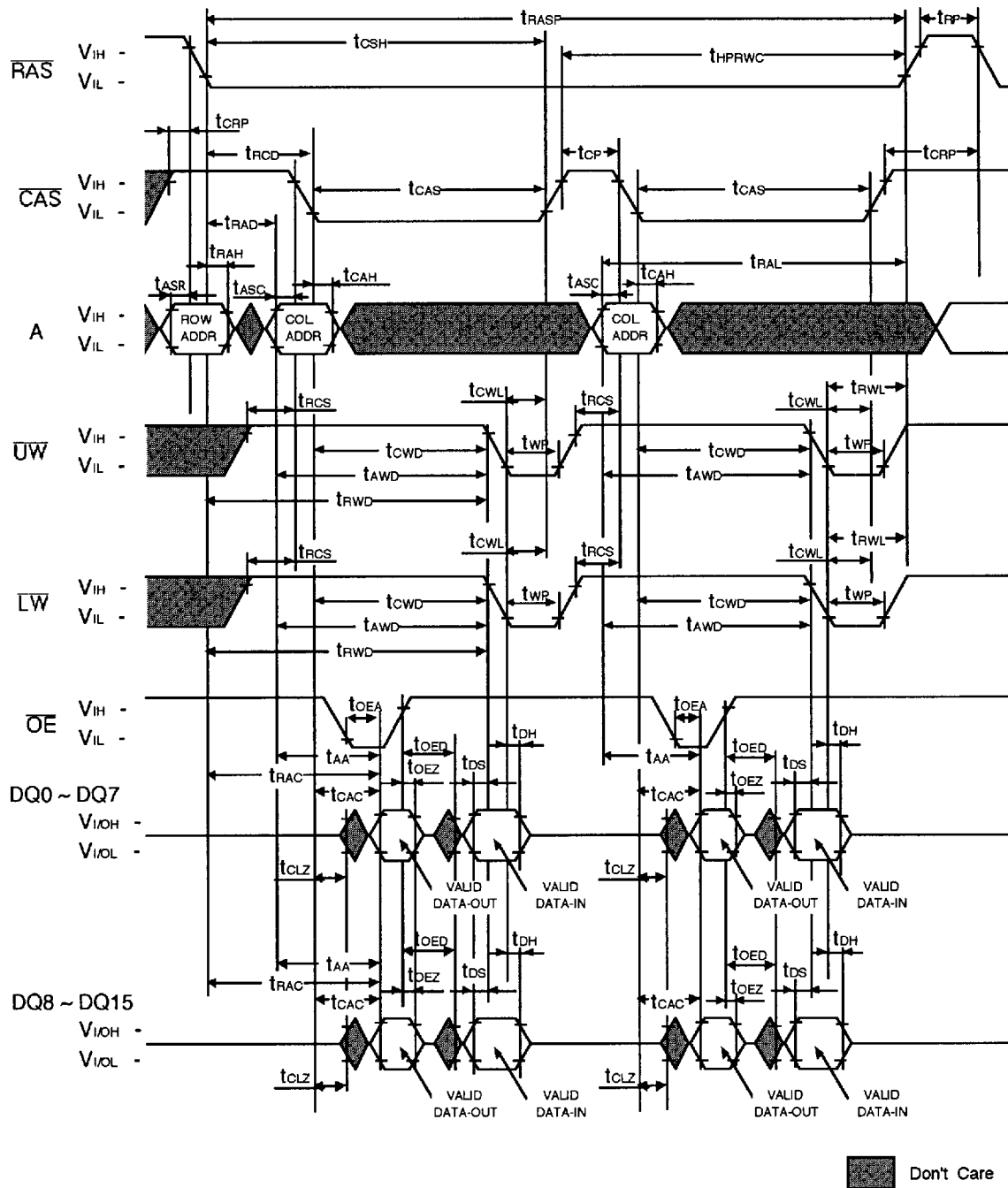


HYPER PAGE MODE UPPER BYTE WRITE CYCLE (EARLY WRITE)

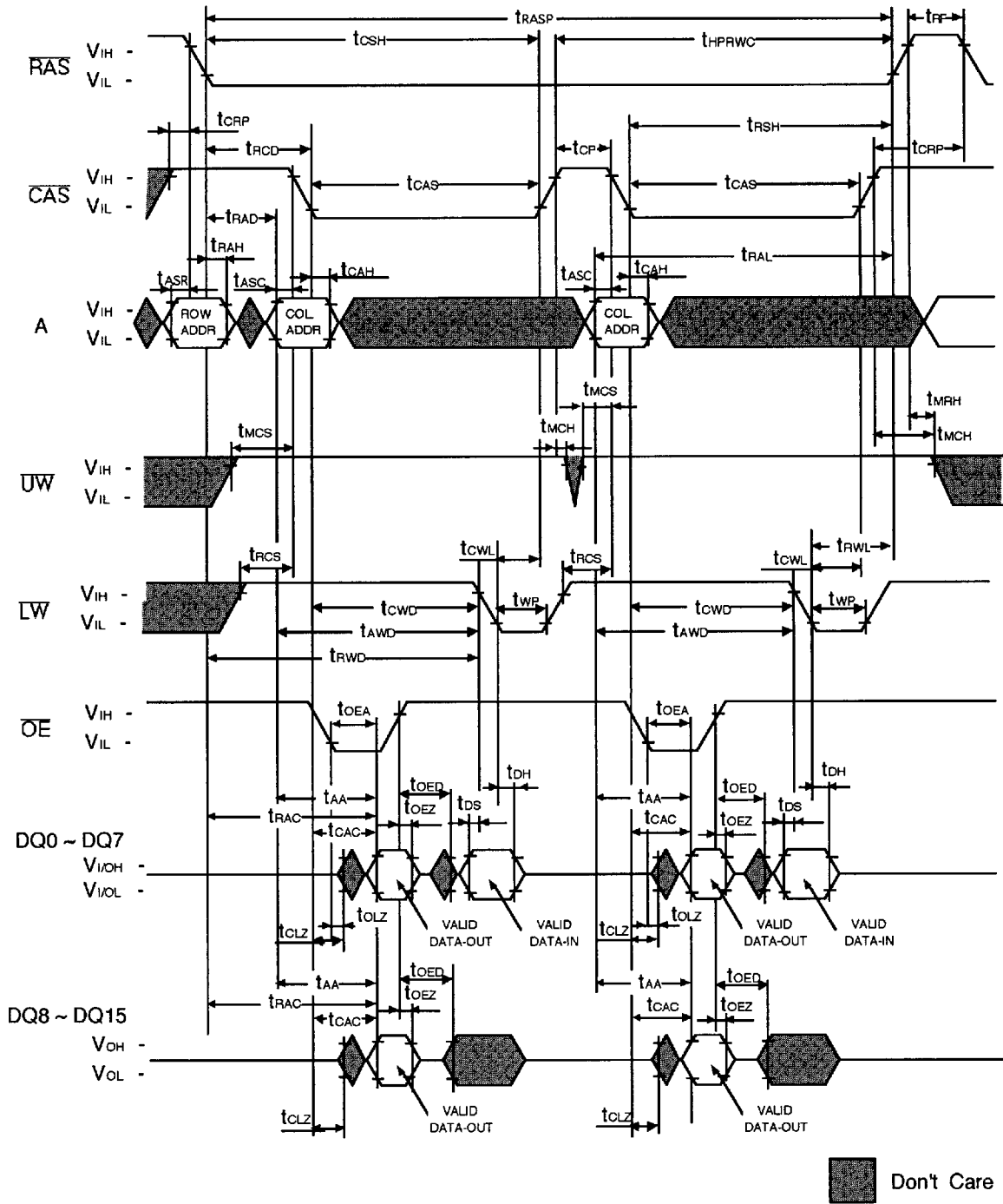
NOTE : D_{OUT} = Open



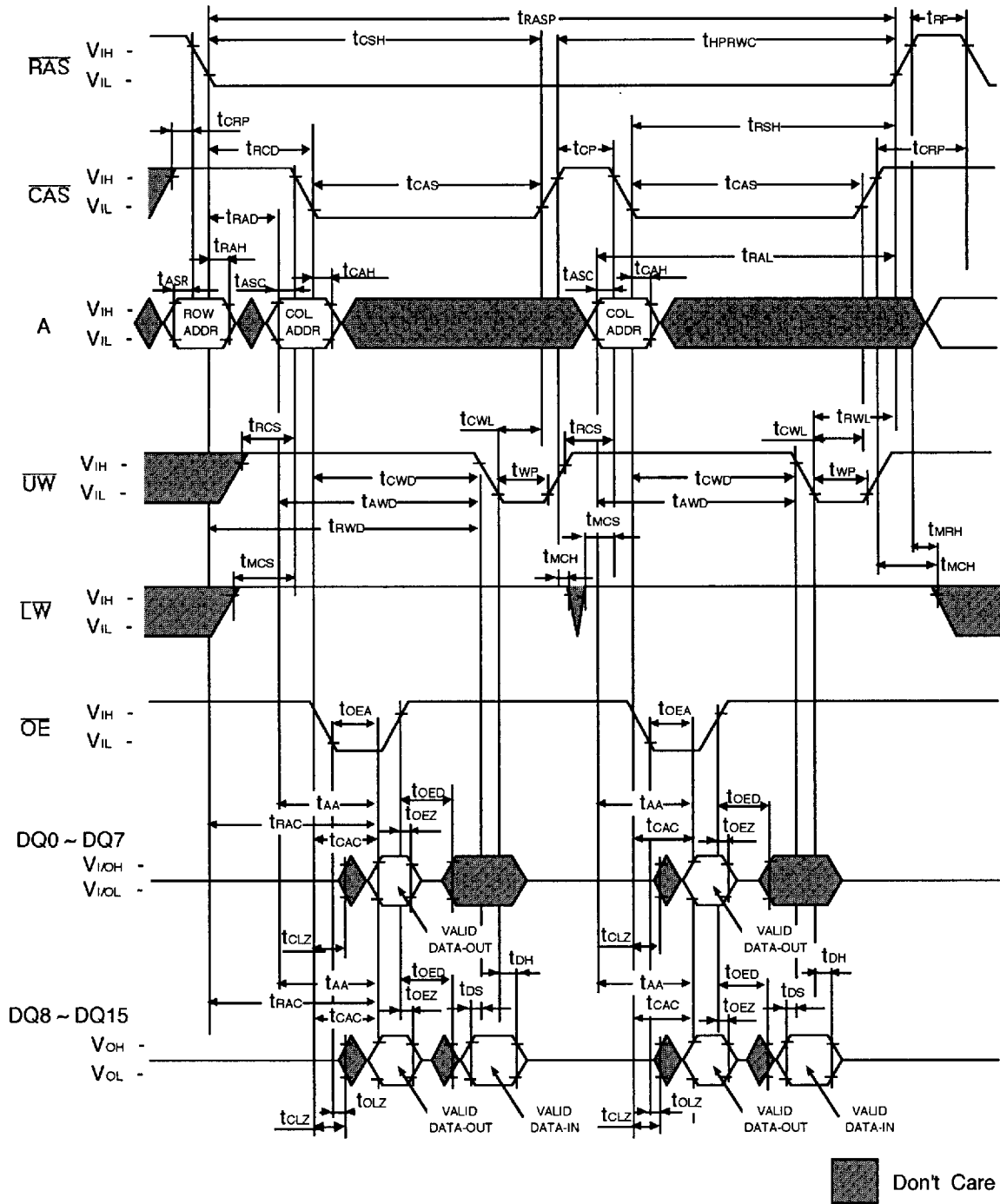
HYPER PAGE MODE WORD READ-MODIFY-WRITE CYCLE



HYPER PAGE MODE LOWER-BYTE-READ-MODIFY-WRITE CYCLE

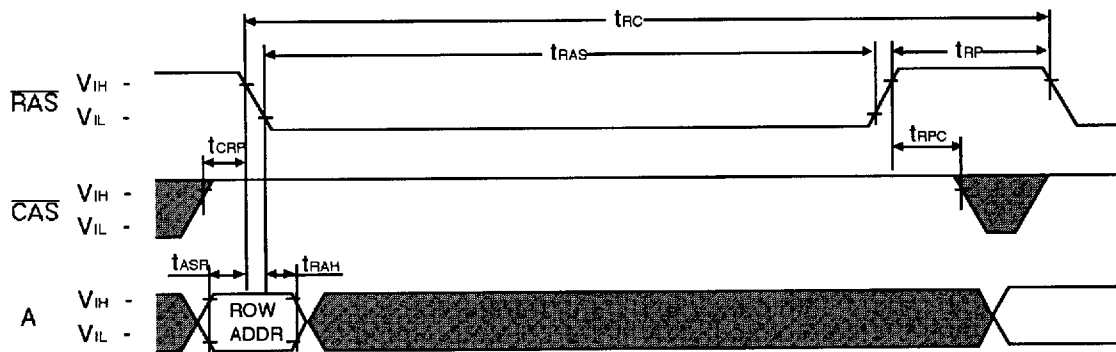


HYPER PAGE MODE UPPER-BYTE-READ-MODIFY-WRITE CYCLE



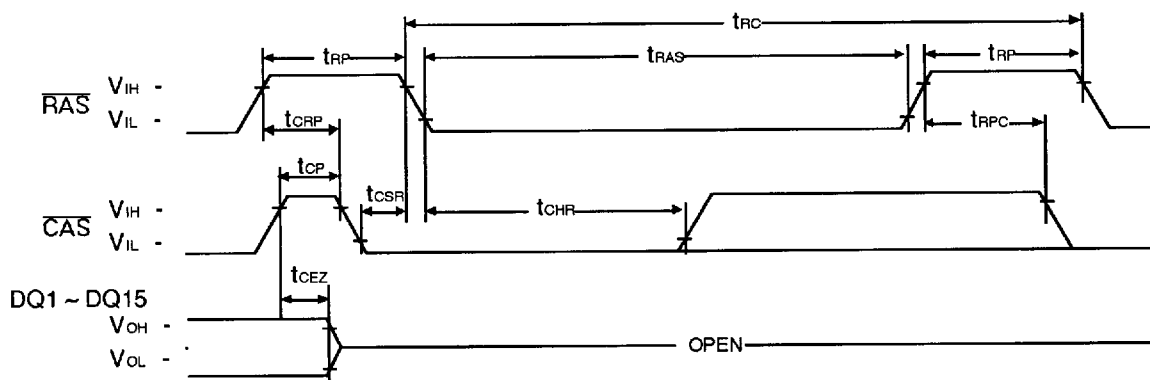
RAS-ONLY REFRESH CYCLE

NOTE : \overline{W} , \overline{OE} , D_{IN} = Don't care
 D_{OUT} = Open



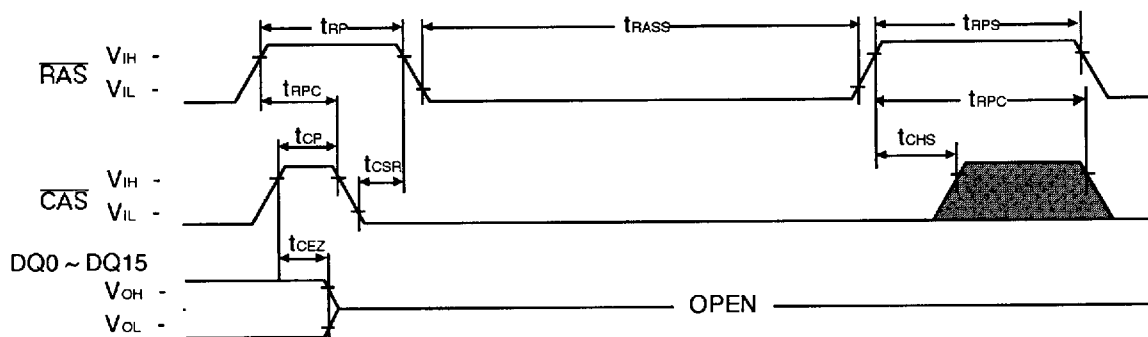
CAS-BEFORE-RAS REFRESH CYCLE

NOTE : \overline{W} , \overline{OE} , A = Don't Care



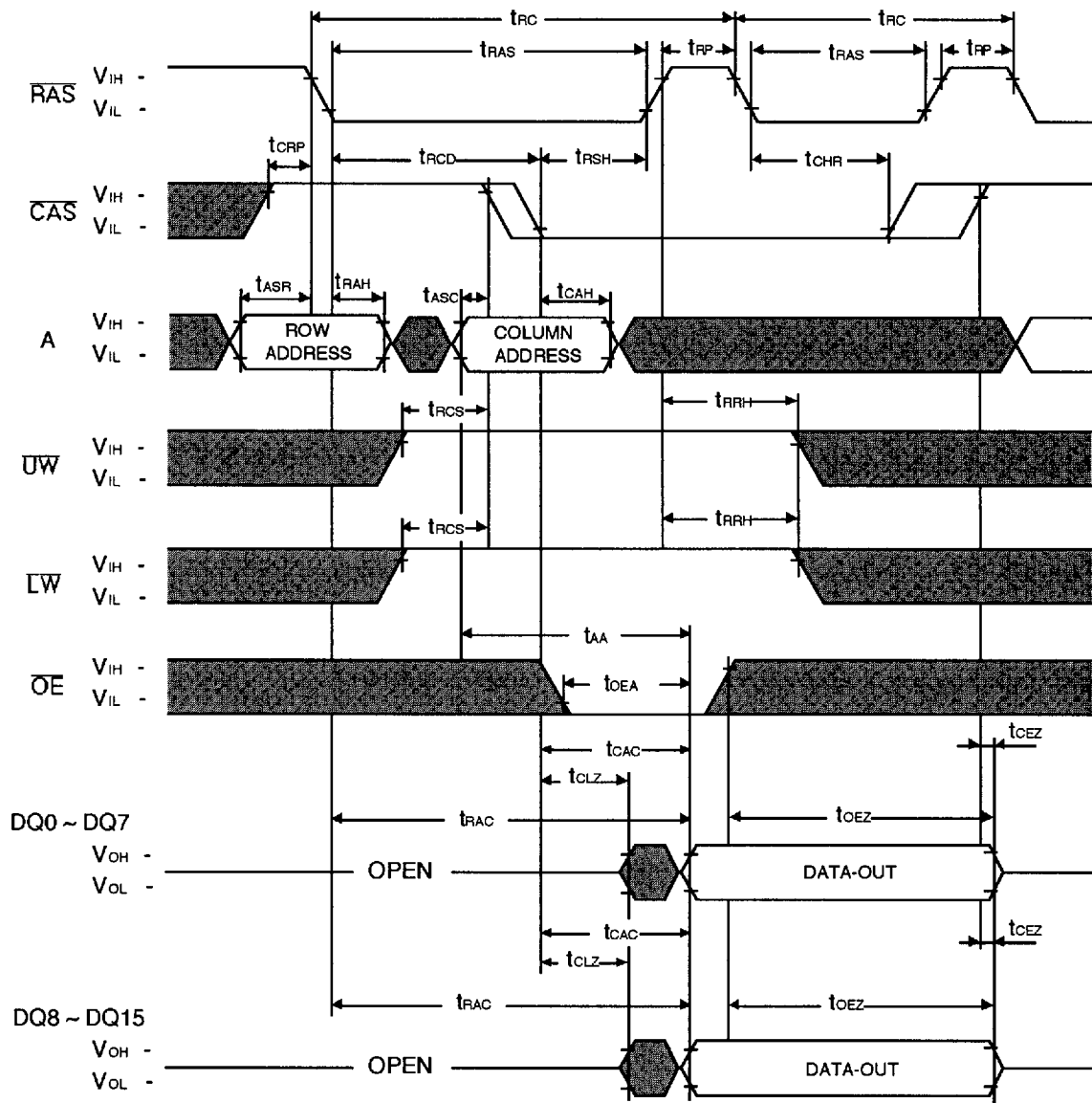
CAS-BEFORE-RAS SELF REFRESH CYCLE

NOTE : \overline{W} , \overline{OE} , A = Don't Care



■ Don't Care

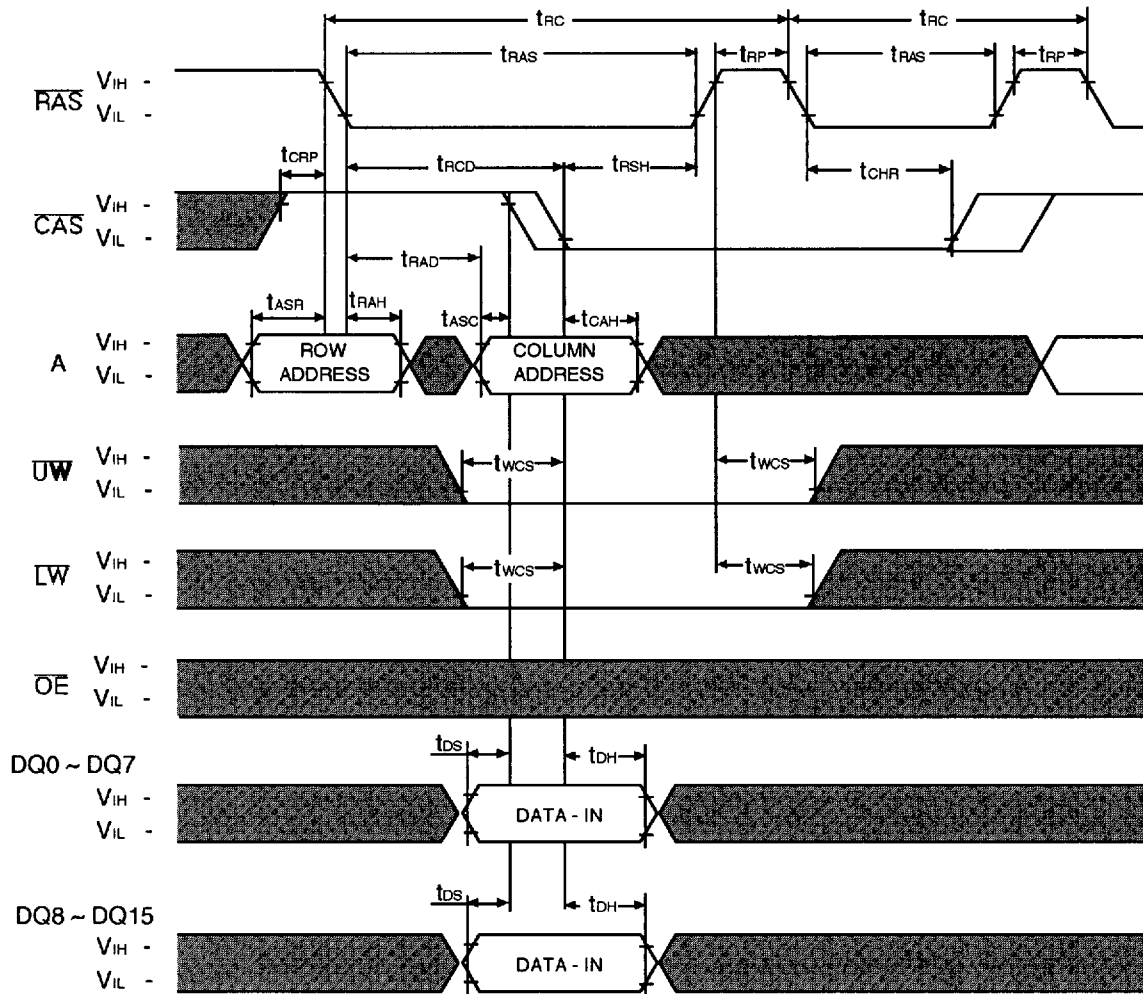
HIDDEN REFRESH CYCLE (READ)



■ Don't Care

HIDDEN REFRESH CYCLE (WRITE)

NOTE : D_{OUT} = OPEN



■ Don't Care

CAS-BEFORE-RAS REFRESH CYCLE TEST CYCLE

